

ABSTRACT

In an electronic component unit, in order to prevent the occurrence of connection trouble between the connecting area of a conductive pattern and the electrode of an electronic component, the surface of connecting area 4a of conductive pattern 4 formed on substrate 1 is roughened, and the protruding electrode 7a of a semiconductor integrated circuit 7 is connected with the roughened surface of connecting area 4a by means of an electroconductive adhesive 8.